

Product Summary

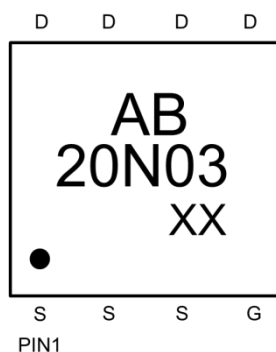
$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	8m Ω @10V	20A
	12m Ω @4.5V	

Feature

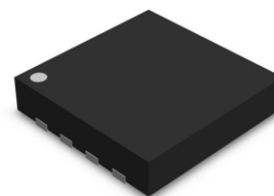
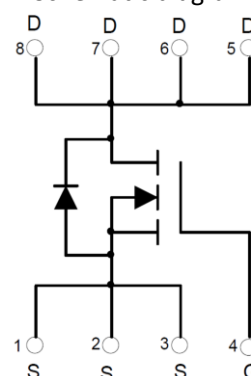
- High cell density trench N-ch MOSFETs
- Super low gate charge
- Advanced high cell density Trench technology

Application

- Battery protection applications
- Load switch

MARKING:


AB20N03= Device code
Solid dot=Pin1 indicator
XX=Date Code

DFN3*3-8L

Schematic diagram

ABSOLUTE MAXIMUM RATINGS ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D^{(1)}$	20	A
Pulsed Drain Current	$I_{DM}^{(1), (2)}$	45	A
Power Dissipation	$P_D^{(3)}$	3	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	42	$^{\circ}\text{C/W}$
Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}\text{C}$

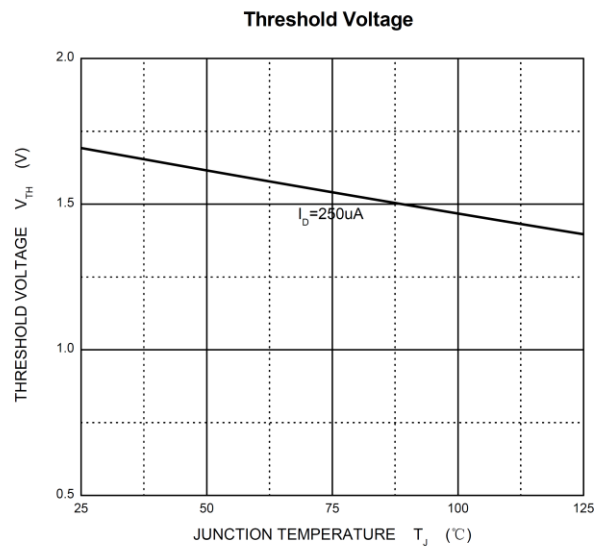
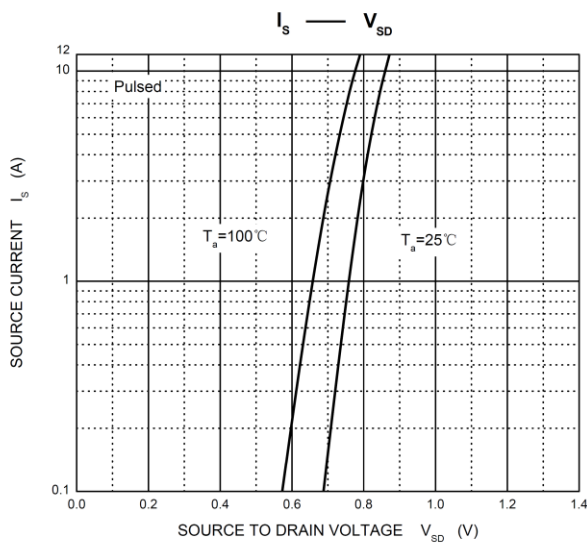
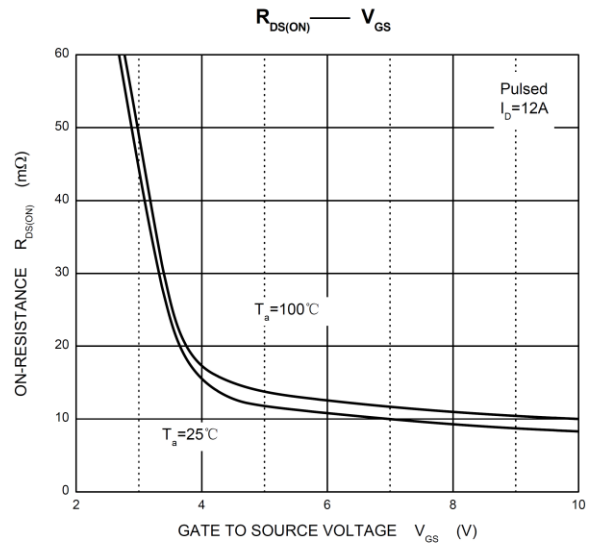
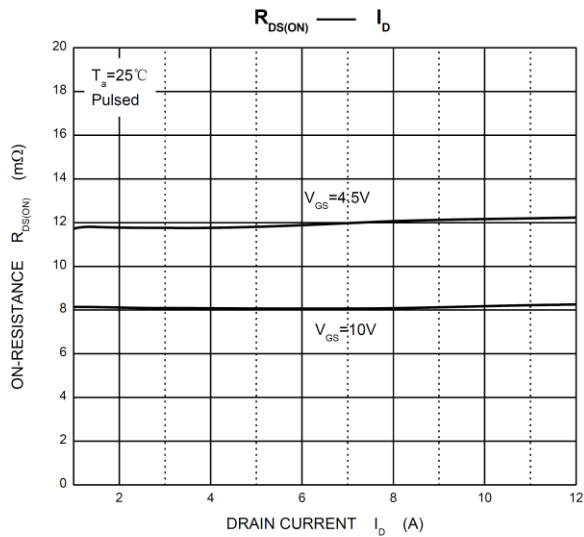
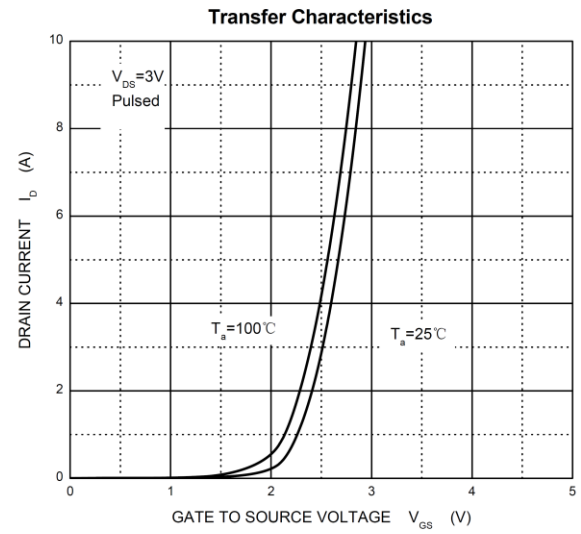
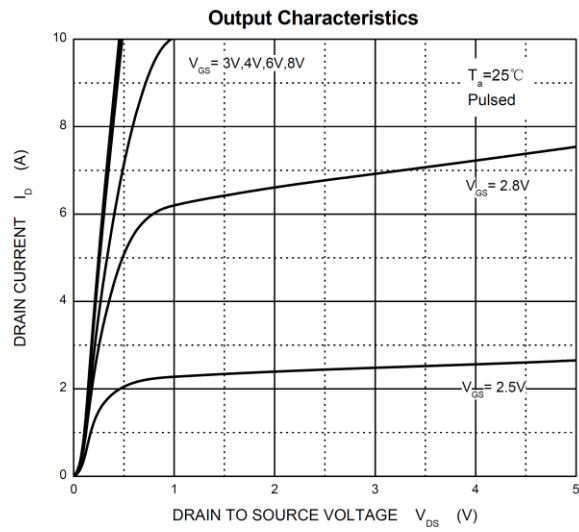
MOSFET ELECTRICAL CHARACTERISTICS (T_J=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} =30V,V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			±100	nA
Gate threshold voltage	V _{GS(th)} ⁽⁴⁾	V _{DS} =V _{GS} , I _D =250μA	1.0	1.7	3.0	V
Drain-source on-resistance	R _{DS(on)} ⁽⁴⁾	V _{GS} =10V, I _D =12A		8	12	mΩ
		V _{GS} =4.5V, I _D =10A		12	18	
Forward tranconductance	g _{FS} ⁽⁴⁾	V _{DS} =5V, I _D =10A	5	12		S
Dynamic characteristics ⁽⁵⁾						
Input capacitance	C _{iSS}	V _{DS} =10V,V _{GS} =0V,f =1MHz		1277		pF
Output capacitance	C _{oSS}			144		
Reverse transfer capacitance	C _{rSS}			134		
Switching Characteristics ⁽⁵⁾						
Total gate charge	Q _g	V _{DS} =15V,V _{GS} =5V,I _D =10A		13.5		nC
Gate-source charge	Q _{gs}			5.6		
Gate-drain charge	Q _{gd}			3.7		
Turn-on delay time	t _{d(on)}	V _{DD} =25V , V _{GS} =10V , R _G =63Ω, R _L =6.7Ω,I _D =1A		31		ns
Turn-on rise time	t _r			22		
Turn-off delay time	t _{d(off)}			105		
Turn-off fall time	t _f			82		
Diode Characteristics						
Continuous Source Current	I _S	V _G =V _D =0V , Force Current			15	A
Pulsed Source Current	I _{SM}				45	
Diode Forward Voltage	V _{SD} ⁽⁴⁾	V _{GS} =0V , I _S =10A , T _J =25℃		0.85	1.2	V

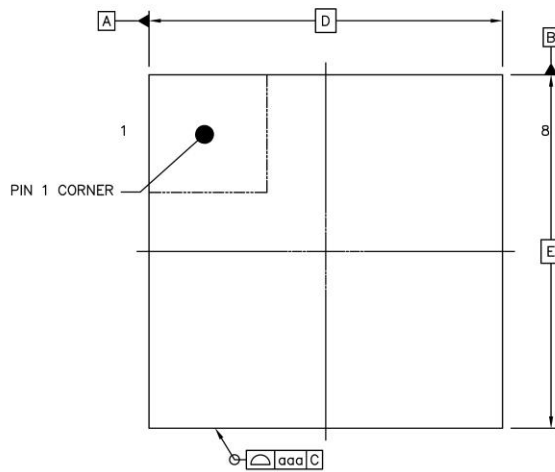
Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper
- 2.Pulse Test:Pulse Width < 10us, Duty Cycle < 0.5%.
- 3.The power dissipation is limited by 150°C junction temperature
- 4.Pulse Test : Pulse width≤300μs, duty cycle≤0.5%.
- 5.Guaranteed by design, not subject to production testing.
- 6.The data is theoretically the same as I_D, in real applications , should be limited by total power dissipation.

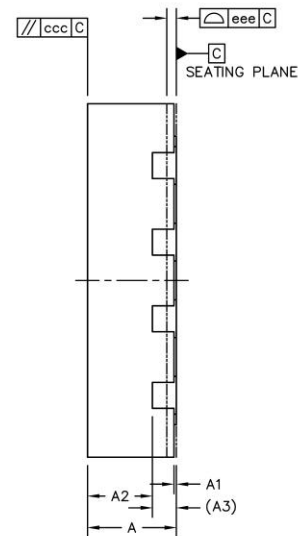
Typical Electrical and Thermal Characteristics



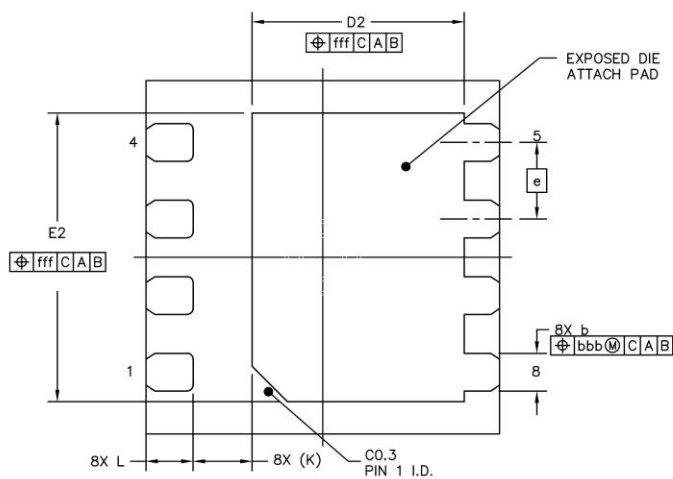
DFN3*3-8L Package Information



TOP VIEW



SIDE VIEW



BOTTOM VIEW

DFN3*3-8L Package Information

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.550TYP		0.022TYP	
A3	0.203REF		0.008REF	
b	0.270	0.370	0.011	0.015
D	3.000BSC		0.118BSC	
E	3.000BSC		0.118BSC	
e	0.650BSC		0.026BSC	
D2	1.700	1.900	0.067	0.075
E2	2.350	2.550	0.093	0.100
L	0.300	0.500	0.012	0.020
K	0.500REF		0.020REF	
aaa	0.100TYP		0.004TYP	
ccc	0.100TYP		0.004TYP	
eee	0.080TYP		0.003TYP	
bbb	0.100TYP		0.004TYP	
fff	0.100TYP		0.004TYP	